



Docket No. 24061.197 (2003-1506)
Customer No. 42717

UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Mong-Song Liang, et al. § Docket No.: 24061.197 (2003-1506)
Serial No.: 10/810,970 § § Examiner: To Be Determined
Filed: March 26, 2004 § § Art Unit: 2812
For: Integrated Treatment Method for § § Conf. No.: 9657
Obtaining Robust Low Dielectric
Constant Materials § §

Commissioner of Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL SHEET TO POWER OF ATTORNEY

In accordance with 37 CFR 1.32 (c)(3) and with reference to the accompanying Power of Attorney, please recognize the following ten patent practitioners as being of record in this application.

Name	Registration Number
David M. O'Dell	42,044
Jeffrey M. Becker	35,442
Timothy F. Bliss	50,925
Andrew S. Ehmke	50,271
Dave R. Hofman	55,272
Wei Wei Jeang	33,305
Julie M. Nickols	50,826
J. Andrew Lowes	40,706
T. Murray Smith	30,222
Chien Wei Chou	41,672

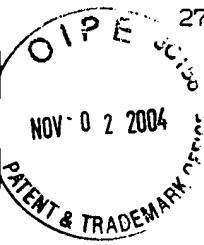
Respectfully submitted,

David M. O'Dell
Registration No. 42,044

Dated: 10-28-04

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Certificate of Mailing	
I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below.	
Name	<u>Sayle Connor</u>
Date	<u>10-29-04</u>



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: § Attorney Docket No.: 24061.197
 Mong-Song Liang et al. § TSMC2003-1506
 §
 Serial No.: Unknown § Customer No. 27683
 §
 Filed: Herewith § Group Art Unit: Unknown
 §
 For: INTEGRATED TREATMENT METHOD § Examiner: Unknown
 FOR OBTAIN ROBUST LOW §
 DIELECTRIC CONSTANT MATERIALS §

Commissioner for Patents
 P. O. Box 1450
 Alexandria, VA 22313-1450

POWER OF ATTORNEY FOR PATENT APPLICATION

As a representative of the Assignee, Taiwan Semiconductor Manufacturing Company, Ltd., I hereby appoint the following attorneys and/or agents to prosecute this application and transact all business in the Patent and Trademark Office connected therewith.

David L. McCombs (Reg. No. 32,271); Jeffrey M. Becker (Reg. No. 35,442); James R. Bell (Reg. No. 26,528); Timothy F. Bliss (Reg. No. 50,925); Randall C. Brown (Reg. No. 31,213); Randall E. Colson (Reg. No. 40,566); Michael A. Davis, Jr. (Reg. No. 35,488); Andrew S. Ehmke (Reg. No. 50,271); Priscilla Ferguson (Reg. No. 42,531); Sarah T. Harris (Reg. No. 35,891); William E. Hickman (Reg. No. 46,771); David R. Hofman (Reg. No. P-55,727); Rita M. Irani (Reg. No. 31,028); Wei Wei Jeang (Reg. No. 33,305); Warren B. Kice (Reg. No. 22,732); J. Andrew Lowes (Reg. No. 40,706); Todd Mattingly (Reg. No. 40,298); Julie Nickols (Reg. No. 50,826); Gloria Norberg (Reg. No. 36,706); David M. O'Dell (Reg. No. 42,044); T. Murray Smith (Reg. No. 30,222); and Chien Wei Chou (Reg. No. 41,672).

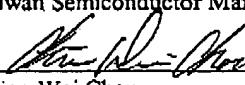
Please address all correspondence and telephone calls regarding this application to:

David M. O'Dell
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The undersigned is the representative for the Assignee of the entire right, title, and interest in the patent application identified above. A copy of the assignment or other documents in the chain of title are attached.

The undersigned (whose title is supplied below) is authorized to act on behalf of the Assignee.

Taiwan Semiconductor Manufacturing Company, Ltd.


 Chien-Wei Chou
 Title: Director, IP Division

Date

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ASSIGNMENT

WHEREAS, we,

(1)	Mong-Song Liang	of	2F, No. 12, Bamboo Rd. 7 Science-Based Industrial Park Hsin-Chu, Taiwan 300, R.O.C.
(2)	Yung-Cheng Lu	of	(address) (city,country)
(3)	Huilin Chang	of	50 Ta-Hsueh Rd., 10F-4 Hsin-Chu, Taiwan 300-50, R.O.C.

have invented certain improvements in

INTEGRATED TREATMENT METHOD FOR OBTAINING ROBUST LOW DIELECTRIC CONSTANT MATERIALS

for which we have executed an application for Letters Patent of the United States of America, filed on March 26, 2004 and assigned application number 10/810,970;

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park Hsin-Chu, Taiwan 300-77, Republic of China, is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

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AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Mong-Song Liang

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Taiwan, R.O.C.

Dated: 08/06/04



Inventor Signature

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Dated: 08/06/04

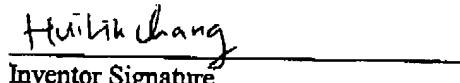


Inventor Signature

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Dated: 08/06/04



Inventor Signature

R-70775.1